Scientech Corp.

MT Hsu 2026/05/12

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Safe Harbor Statement

- **This Presentation contains certain forward-looking statements that are based on current expectations and are subject to known and unknown risks and uncertainties that could cause actual results to differ materially from those expressed or implied by such statements.**

- **Except as required by law, we undertake no obligation to update any forward-looking statements, whether as a result of new information, future events or otherwise.**

Agenda

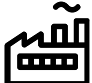
About Us

Overview | Milestones | Location | Organization

Overview

Product and Technology

- Equipment Design and Manufacturing
- Wafer Reclaim
- Representative



Industries We Serve

- Semiconductor (Front-End and Advanced Packaging)
- Compound Semiconductor
- LED / Mini LED / Micro LED
- Flat Panel Display (TFT-LCD, AMOLED, Touch Panel)

Established:
1979
Taipei, Taiwan

Capital:
US$ 27 Million
TWSE:3583

Employees:
>1,100
(Worldwide)

Employees

Over 1,100 Employees

Representative

- 145 in Taiwan
- 130 in China
- 70% in Service and Process Support

Equipment Design and Maf’g

- 430 in Total
- 130+ in R&D, Process and Design

Wafer Reclaim

- 310 in Total

Administration

- 85 in Total

Milestones

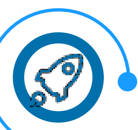
1979

1985
Branch Office
in Hsinchu, Taiwan

1995
Subsidiary
in CA, USA

2001
Subsidiary
in Shanghai, China

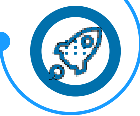
2002
Singapore



2003
Equipment Manufacture
Department Established

2004
New Hsinchu
Office Opened

2006
Wafer Reclaim
Business Launched



2007
New Factory
in Hukou Opened

2013
Publicly Listed in
Taiwan Stock Market

2021
Subsidiary
in Villach, Austria

2025
Over 1000 Equipment
Sales Achievement

Locations - Taiwan

Taipei Headquarter

HsinChu Office

HuKou Factory

- Equipment Design and Manufacturing
  - Equipped With Class 10/1,000/10,000 Clean Room
- Wafer Reclaim

Taichung Office

Chiayi Office

Tainan Office

Kaohsiung Office

Locations - Worldwide

Europe

Villach, Austria (2020)

- Sales and Service Office to support European customers
- Interface with our factory and European Customers
- New Product / PRODUCTS Development

China

- Beijing office (2004)
- Dalian office (2012)
- Xian (2013)
- Chongqing office (2010)
- Changzhou (2012)
- Wuxi office (2003)
- Shanghai Office (2001)
- Wuhu office (2013)
- Xiamen office (2011)
- Huizhou office (2013)
- Qunming Office (2002)

USA

Santa Clara, CA (1994)

- Sales and Service Office
- Interface with Principals and U.S. Customers
- New Product / PRODUCTS Development

Organization

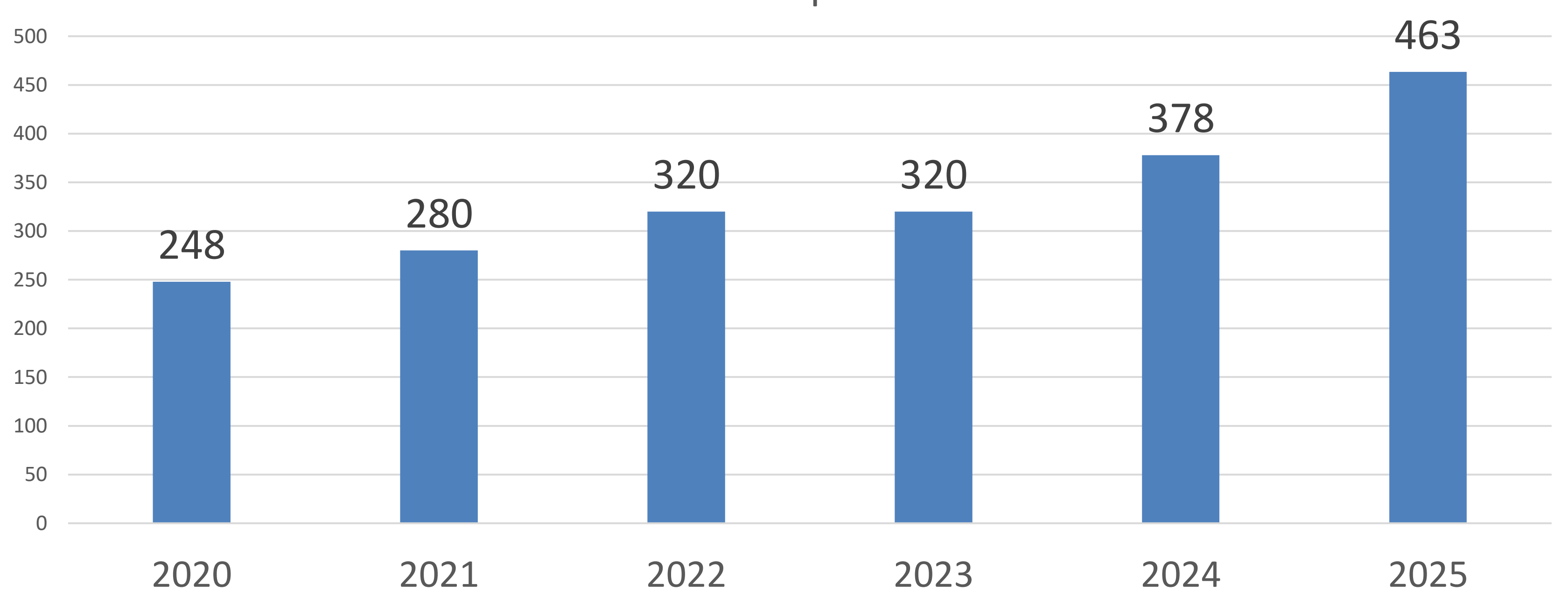
- Scientech
  - General Admin.
  - New Projects
  - Equipment M'fg
  - Wafer Reclaim
  - Semi / Opto Rep.
  - Taiwan Offices
  - China Offices
  - USA Office
  - Europe Office
  - Japan Agent
  - Korea Agent
  - S'pore Agent

Products & Services

Wafer Reclaim | Equipment Manufacturing and Design | Representative

R&D Expenses

Units：NT $ M	2020	2021	2022	2023	2024	2025	2026/Q1
R&D Expenses	248	280	320	320	378	463	152
Expenses as % of Revenue	6.9%	6.0%	5.7%	5.7%	3.9%	4.1%	4.9%
Expenses as % of Manufacturing	16.5%	14.9%	15.3%	15.7%	11.3%	9.8%	9.9%



Patents

- **The cumulative number of patents on file is 204, and 50 applications are pending.**

2015	2016	2017	2018	2019	2020	2021	2022	2023	2024	Dec-25
25	28	33	44	74	109	136	154	170	182	204

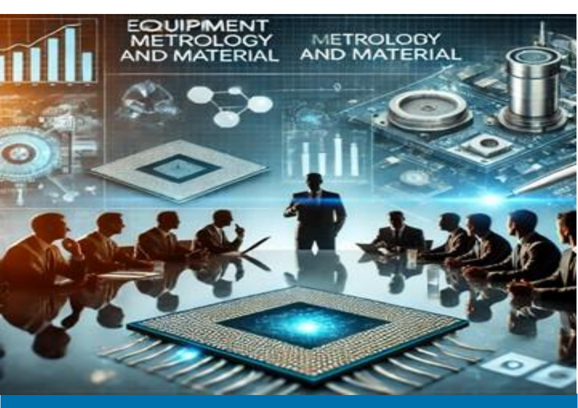
Products

Equipment Design and Manufacturing

- Advanced Package
- FEOL
- Mask
- Compound
- etc...

Wafer Reclaim

- 12” Si Wafer



Representative

- Equipment/Metrology
- Sub-System
- Material
- Repair and Refurbish

Wafer Reclaim Service

Advanced Clean Technology
- **19nm Particle**
- **Low Trace Metal (<1E9)**

Advanced Defect Inspection (SP1/SP2/SP5/SP7)

12" Si Wafer

- Capacity: 210K / Month
- Cu and Non-Cu Process

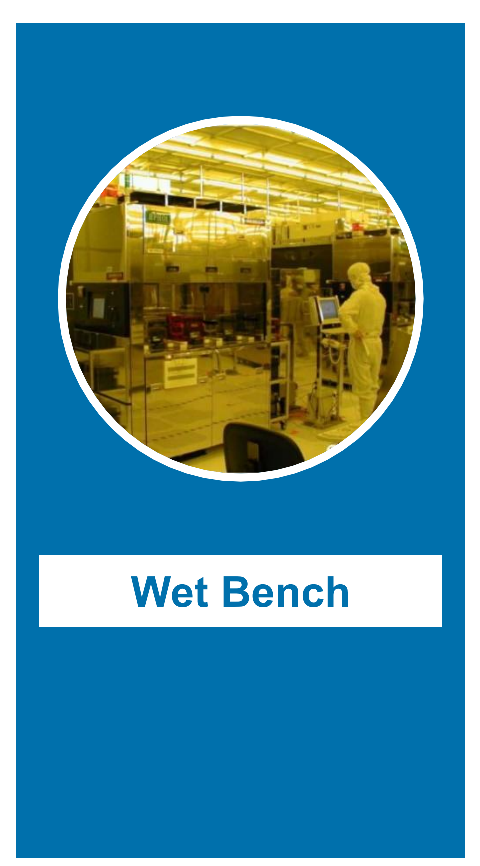
Capacity Expansion

- Additional 40K / Month by end of 2026

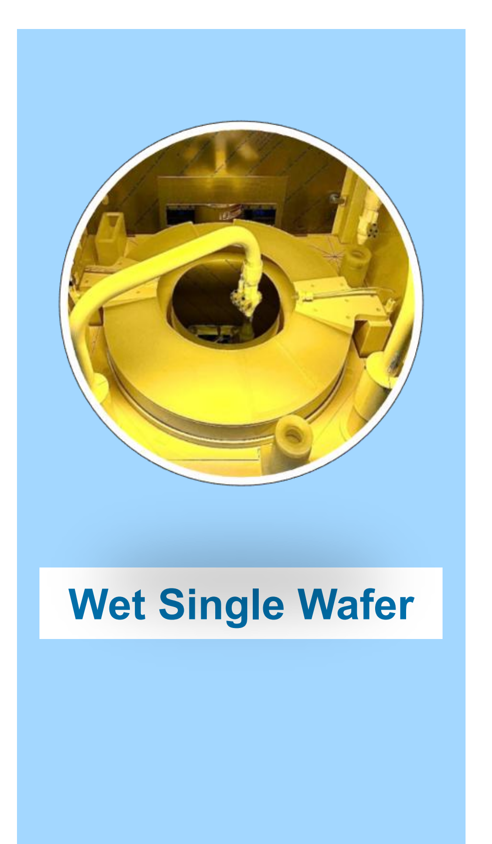
Complete Polishing Process
- **Single/Double Side Polish**
- **Final Haze Polish**

Super Flatness (GBIR < 0.5mm)

Equipment Design & MFG

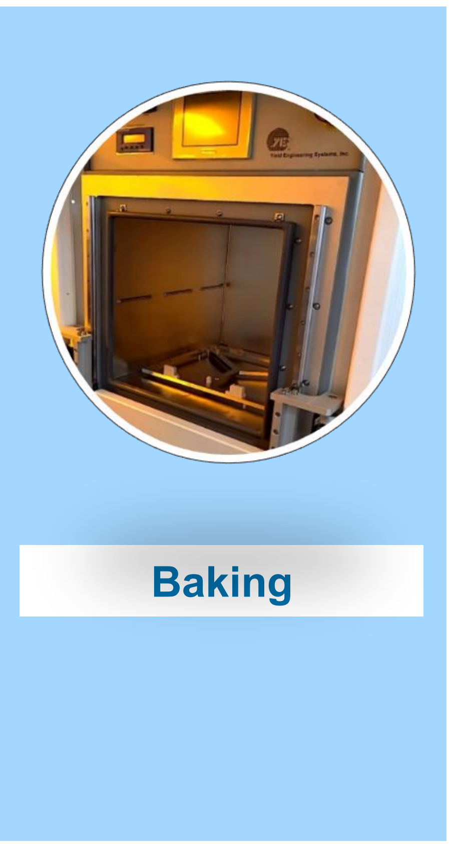


Wet Bench



Wet Single Wafer

TBDB



Baking

Equipment Design & MFG

Wet Process – Bench

Application

- Semiconductor: FEOL, BEOL, Compound
- Advanced Packaging/Bumping…

Features

- Cassette type or Cassette-less type
- Adopted by big international companies
- Leading-edge technologies

Process

- Etch: Metal/Oxide/Nitride remove
- Stripper: PR/PI strip, Polymer remove
- Clean: Pre/Post/Flux clean
- Electro-less Plating: Zn/Ni/Pd/Au

Equipment Design & MFG

Wet Process – Single Wafer

Application

- Semiconductor: BEOL, FEOL, Compound
- Advanced Packaging/Bumping

Features

- Soak/Immersion + Single
- Adopted by big international companies
- Leading-edge technologies

Process

- UBM / Metal Etch
- Flux Clean (Hot DIW)
- PR Strip
- Wafer Clean (APC, Soft spray)
- Final Clean/Mask Clean/Frame Clean

Equipment Design & MFG

Temporary Bonding De-Bonding

- IGBT & SiC Power Device
- Advanced Packaging for Semiconductor

- User-friendly graphical user interface
- Adopted by big international companies
- Leading-edge technologies

Process

- Temporary Bonding
- Temporary De-bonding
- Release Layer Coating
- Carrier (Glass) Recycling

Equipment Design & MFG

Moisture Baking

Application

- Semiconductor: BEOL
- Advanced Packaging for Semiconductor

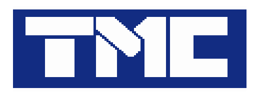
Features

- Availability for horizontal or vertical process
- High precision temperature control
- Weight handling capacity up to 23kg per lot

Process

- Pre-underfill baking
- Pre-mold baking
- DFR Hard Bake

Trading (Agent/Distributor)

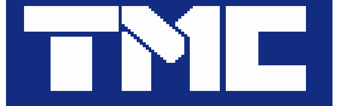


NOVA PROCESS INSIGHT

Multiple Apps

Exclusivity

Long Term Partnership



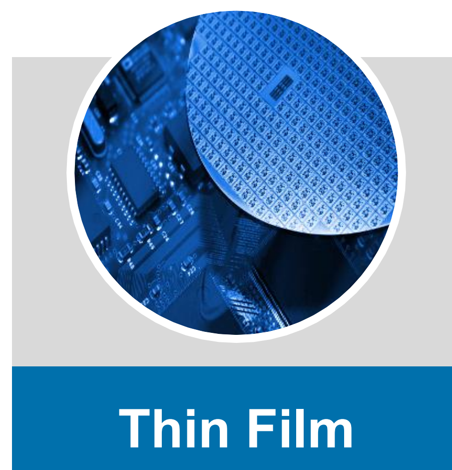
Representative Product Lines

Lithography

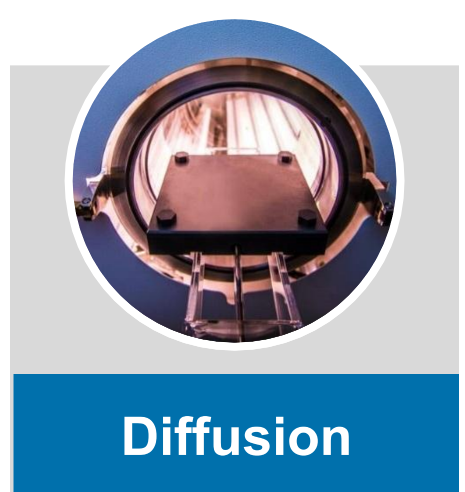
ESOL

USHIO

Etch



Thin Film



Diffusion

Representative Product Lines

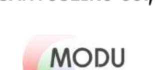
Metrology

Sub-Systems

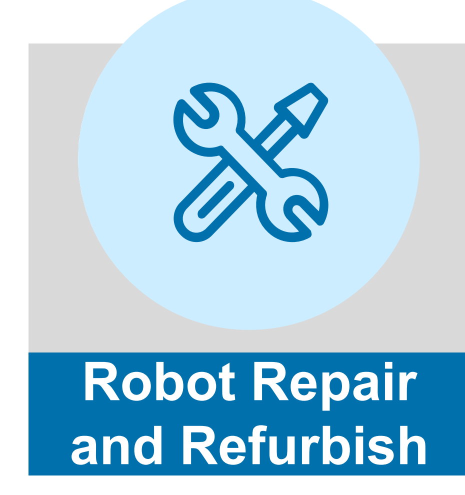
Package & Material

sempro

MIRTEC



GP 群翊 GROUP



Robot Repair and Refurbish

Corporate Governance

Certificates

Year	Certificate	Description
2007	ISO 9001	Quality Management
2010	ISO 14001	Environmental Management
2016	ISO 45001	Occupational Health and Safety Management
2019	ISO 27001	Information Security Management
2021	ISO 22301	Business Continuity Management
2022	RBA	Responsible Business Alliance Online Member
2024	ISO 50001	Energy Management
2025	ISO56005	Innovation Management

Sustainability Report Officially Released since 2024/08

Sustainable Development

Environmental
Social
Governance

Eco-Friendly Manufacturing

Safe And Warm Working Environment

Operating With Integrity

Contributing To Society

Exhibition

Exhibition

Financial Results

Income Statement

Units：NT $ M	2020	2021	2022	2023	2024	2025	2026/Q1
Revenues	3,580	4,684	5,650	6,911	9,688	11,371	3,120
Gross Profit	1,456	1,667	2,084	2,201	2,906	3,814	1,119
Operating Expenses	991	1,112	1,374	1,483	1,790	2,238	645
Operating Income	465	555	710	718	1116	1,576	474
Income Before Tax	389	524	736	860	1277	1,540	441
Net profit attributable to:Owners of the Company	305	420	568	650	927	1,110	333
EPS	**3.80**	**5.23**	**7.08**	**8.10**	**11.54**	**13.82**	**4.14**
Gross Margin	41%	36%	37%	32%	30%	34%	36%
Operating Margin	13%	12%	13%	10%	12%	14%	15%
Income Before Tax Margin	11%	11%	13%	12%	13%	14%	14%

Annual Revenue

Units NT $ M	2020	2021	2022	2023	2024	2025	2025/Q1	2026/Q1
Revenue	3,580	4,684	5,650	6,911	9,688	11,372	2,814	3,120

EPS

UNIT：NTD	2020	2021	2022	2023	2024	2025
EPS	3.80	5.23	7.08	8.10	11.54	13.82

Equipment Revenue

SALES **Units NT $ K**	2020	2021	2022	2023	2024	2025	2026/Q1	2026
Equipment	**931,518**	**1,134,379**	**1,207,789**	**1,325,760**	**2,590,217**	**3,715,167**	**1,255,868**	

Equipment

~ US$ 118M

	2020	2021	2022	2023	2024	2025
Equipment	931,518	1,134,379	1,207,789	1,325,760	2,590,217	3,715,167

Y-axis: -, 500,000, 1,000,000, 1,500,000, 2,000,000, 2,500,000, 3,000,000, 3,500,000, 4,000,000

Wafer Reclaim Revenue

SALES **Units NT $ K**	2020	2021	2022	2023	2024	2025	2026/Q1	2026
Wafer Reclaim	**575,527**	**716,779**	**864,409**	**855,320**	**762,958**	**1,008,562**	**277,112**	↗

Manufacturing Revenue

SALES **Units NT $ K**	2020	2021	2022	2023	2024	2025	2026/Q1	2026
Manufacturing	**1,507,045**	**1,851,158**	**2,072,198**	**2,181,080**	**3,353,175**	**4,723,729**	**1,532,980**	↗

~ US$ 150M

Manufacturing

Year	Manufacturing
2020	1,507,045
2021	1,851,158
2022	2,072,198
2023	2,181,080
2024	3,353,175
2025	4,723,729

Trading Revenue

SALES **Units NT $ K**	2020	2021	2022	2023	2024	2025	2026/Q1	2026
Trading	**2,072,958**	**2,832,629**	**3,577,788**	**4,730,901**	**6,335,105**	**6,647,828**	**1,587,342**	→

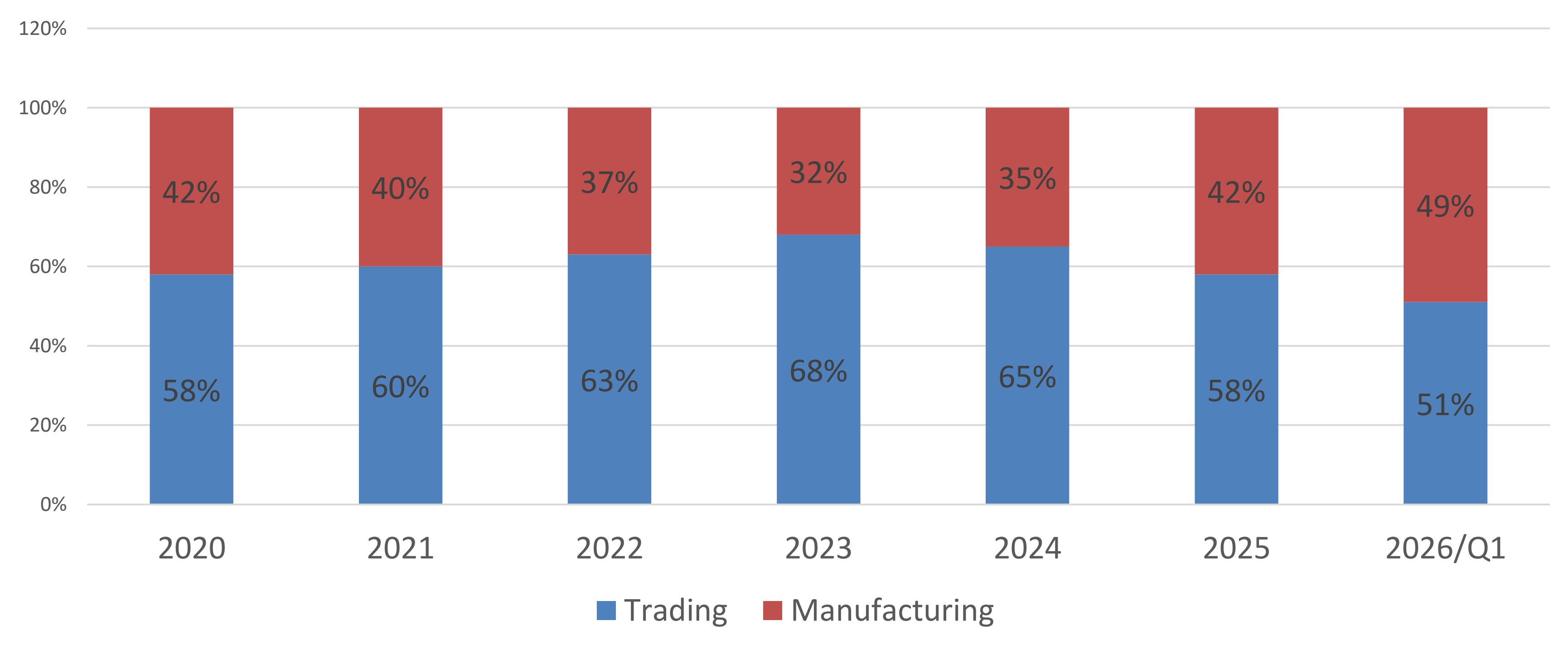
Trading

~ US$ 210M

	2020	2021	2022	2023	2024	2025
Trading	2,072,958	2,832,629	3,577,788	4,730,901	6,335,105	6,647,828

Products Mix – Revenue

Units：%	2020	2021	2022	2023	2024	2025	2026/Q1	2026	Gross Margin
Trading	58	60	63	68	65	58	51	<**50%**	Below Average
Manufacturing	42	40	37	32	35	42	49	>**50%**	Above Average



Future Outlook

Expansion Roadmap

- 2023: New equipment production base in Hukou (off-site)
- 2024: Expansion of existing equipment production at Hukou Plant
- 2025 Q4: Wafer Reclaim Capacity 50K/Month at Hukou Plant
- 2026 Q1: New Office in Shanghai
- 2026 Q4: Wafer Reclaim Capacity 40K/Month at Hukou Plant
- 2026 Q4: 9,000 M^2 (2,700坪) new building (Plant II) for EQPT MFG, and Warehouse next to Hukou Plant (Plant I)
- 2027 Q4: 22,000 M^2 (6,600坪) new building for EQPT MFG, Office and Warehouse in Tainan (southern Taiwan)
- 2027: Wafer Reclaim Capacity 50K/Month at Hukou Plant

Capex / Investment

Capex	NTD K	USD K
Wafer Reclaim 50K Expansion	1,450,000	48,000
Wafer Reclaim 40K Expansion	300,000	10,000
Shanghai Office	180,000	6,000
Hukou Factory II	550,000	18,000
Tainan Factorry	850,000	31,000
Sum	**3,305,000**	**113,000**

Capex	2024	2025	2026
NTD K	546,000	1,250,000	1,750,000
USD K	**18,000**	**41,000**	**58,000**

Other Invest.	2024	2025	2026
NTD K	215,000	109,000	43,000
USD K	7,000	3,600	1,400

Key Highlights

- **Semiconductor CAGR to support our aggressive investment.**
- **Semiconductor Market Size**
  - **2024: 640B**
  - **2025: 750B**
  - **2026: 900B – 1Trillion**
- **TSMC's earning call:**
  - **CAGR for AI Accelerator Chips raised from mid-40% to mid-to-high 50% range during 2024-2029**
  - **Total revenue CAGR raised from 20% to 25% during 2024 to 2029**

Excellent Production Support

TSMC 2024 Outstanding Suppliers Award

tsmc
2024 TSMC SUPPLY CHAIN MANAGEMENT FORUM
Excellent Production Support in Advanced Packaging
SCIENTECH

https://pr.tsmc.com/english/news/3192

Thank You!

https://www.scientech.com.tw